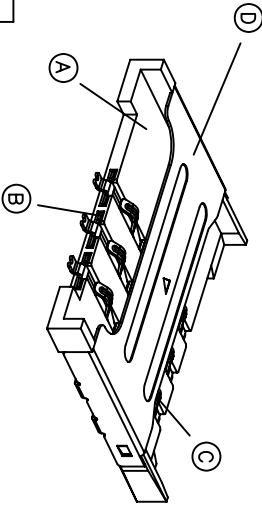
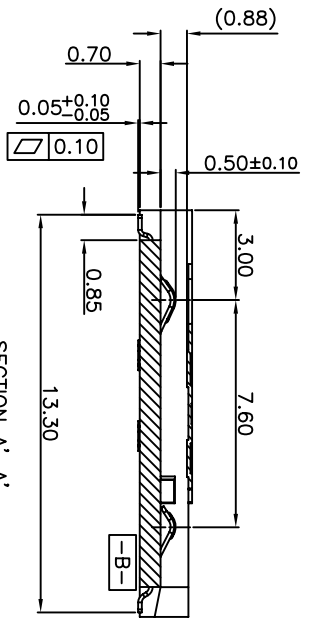
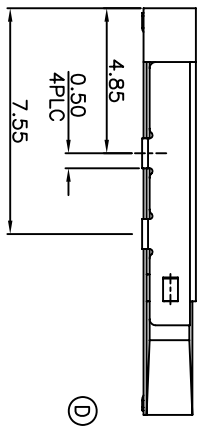
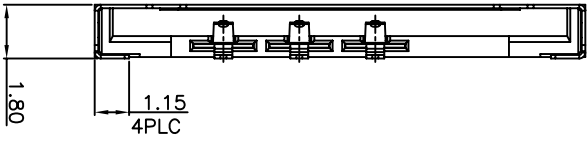
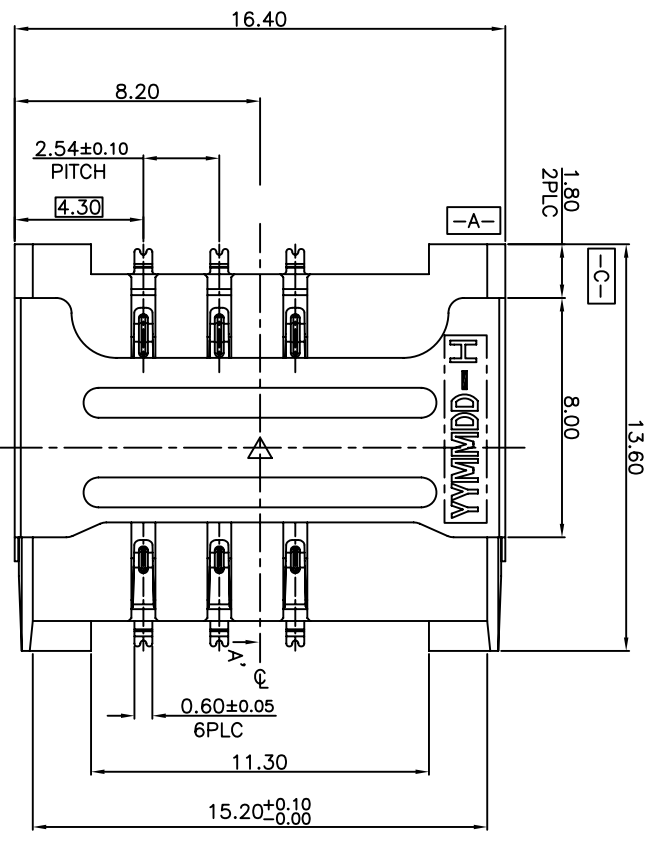


REV.	ECN NO OR DESCRIPTION	REVISED	DATE
A	PDR NO: S090423-6A	BOYE.QI	2009.05.21



- NOTES:
- ELECTRICAL PERFORMANCES:
 - CURRENT RATING: 0.50 A MAX.
 - CONTACT RESISTANCE: 50 mΩ MAX.
 - INSULATION RESISTANCE: 100 MΩ MIN.
 - DIELECTRIC WITHS TANDING VOLTAGE: 250V AC FOR 1 MINUTE.
 - MECHANICAL PERFORMANCES:
 - CONTACT NORMAL FORCE: 0.30N MIN. AT DEFLECTION.
 - MECHANICAL OPERATION: 5000 CYCLES.
 - OPERATING TEMPERATURE: -40°C TO 85°C.
 - HALOGEN FREE PRODUCT IDENTIFICATION MARK ON PRODUCT:
 - FOR LEAD-FREE PRODUCT.
 - SOLDERING HEAT RESISTANCE: 260°C 10 SEC.
 - PRINTED DATE CODE "YYMMDD" ON TOP OF CONNECTOR.

DATE CODE: YYMMDD

 DD: DAY
 MM: MONTH
 YY: YEAR

NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR
D	COVER	1	STAINLESS STEEL,T=0.12	Gold flash Over Ni50u"
C	CONTACT-2	3	PHOSPHOR BRONZE,T=0.12	Au on Contact Area. Gold flash on other area. Over Nickel plating.
B	CONTACT-1	3	PHOSPHOR BRONZE,T=0.12	Au on Contact Area. Gold flash on other area. Over Nickel plating.
A	BODY	1	HIGH TEMP.U94V-0	BLACK

UNLESS OTHERWISE SPECIFIED TOLERANCES

DECIMALS: ANGLES:

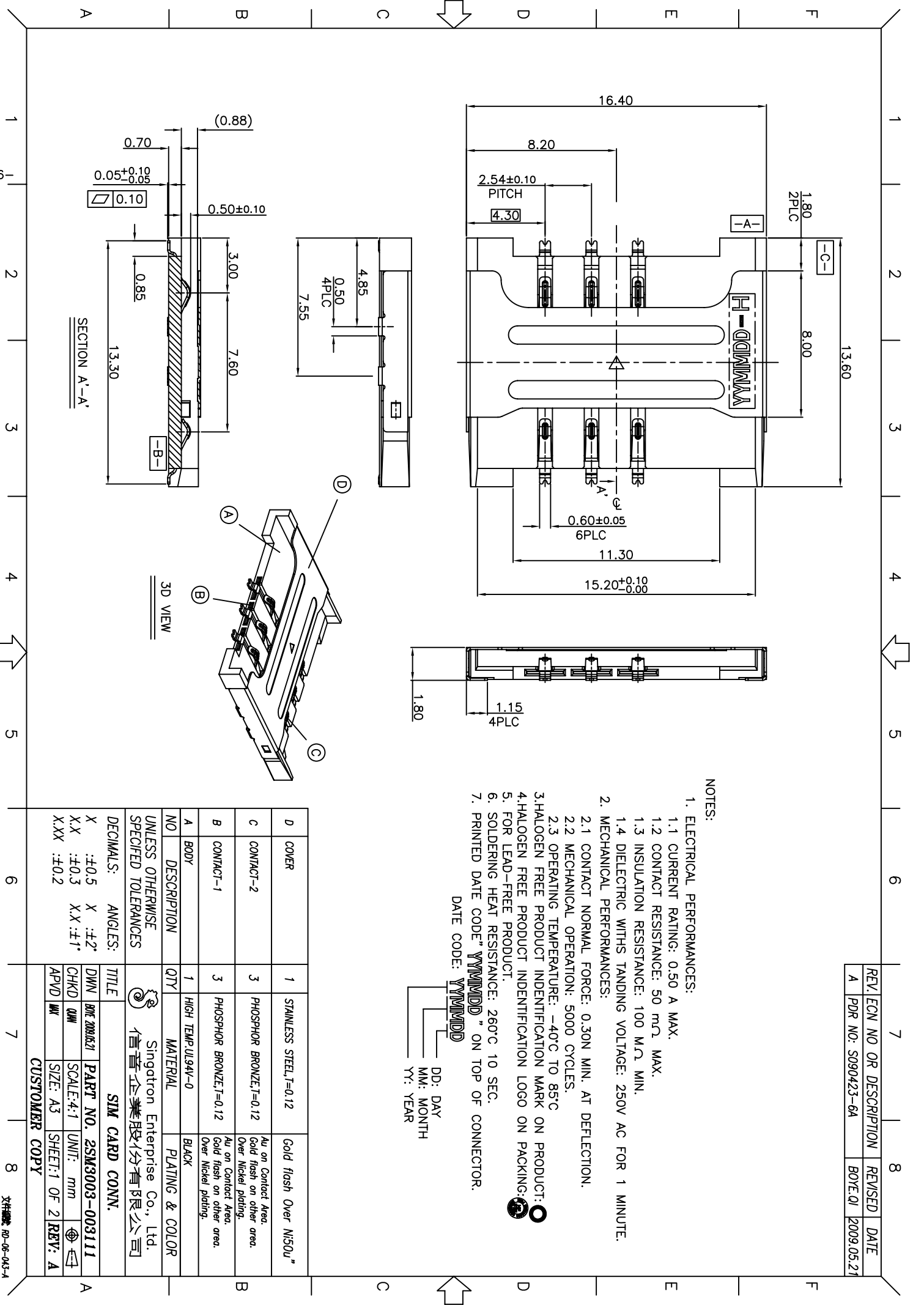
X :±0.5 X :±2°
 X.X :±0.3 X.X :±1°
 X.XX :±0.2

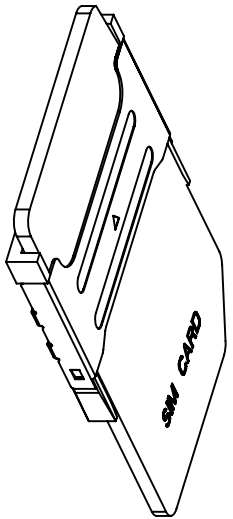
Singatop Enterprise Co., Ltd.
 信普企業股份有限公司

TITLE: SIM CARD CONN.

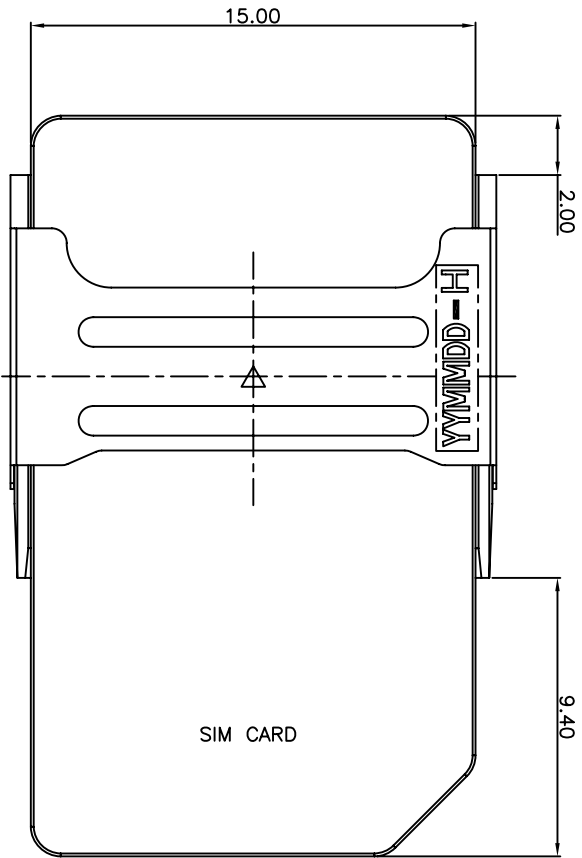
DWN DATE: 2009.05.21 PART NO. SSM3003-003111
 CHKD QM SCALE: 4:1 UNIT: mm
 APVD MW SIZE: A3 SHEET: 1 OF 2 REV: A

CUSTOMER COPY

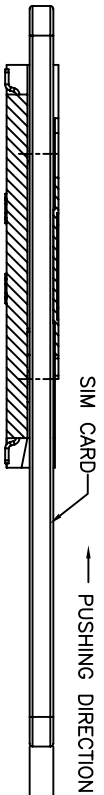




3D VIEW



SIM CARD

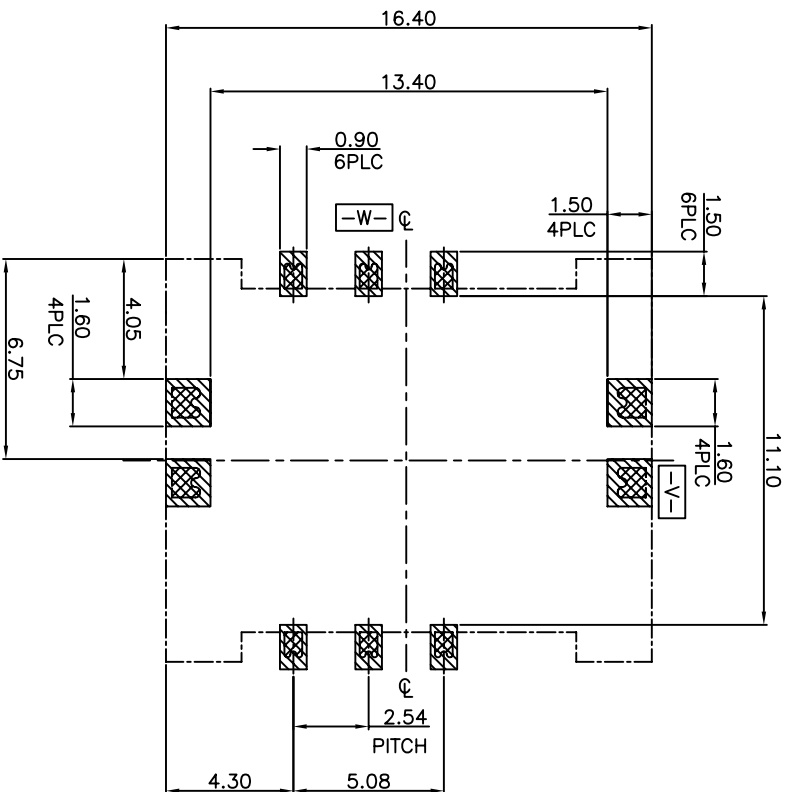


SIM CARD

PUSHING DIRECTION

USE GUIDE

(0.80)



RECOMMENDED P.C.B LAYOUT(TOP VIEW)
TOLERANCE $\pm 0.05\text{mm}$

REV.	ECN NO OR DESCRIPTION	REVISED	DATE
A	PDR NO: S090423-6A	BOYE.QI	2009.05.21

NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR
	UNLESS OTHERWISE SPECIFIED TOLERANCES			
	DECIMALS:			
X	± 0.5	X	$\pm 2^\circ$	
X,X	± 0.3	X,X	$\pm 1^\circ$	
X,XX	± 0.2			
	TITLE		SIM CARD CONN.	
DWN	DATE: 2009.05.21		PART NO. 2SM3003-003111	
CHKD	QW		SCALE: 4:1	UNIT: mm
APVD	HW		SIZE: A3	SHEET: 2 OF 2
				REV: A

CUSTOMER COPY